

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
Koji MISHIMA et al. :
Serial No. NEW : **Attn: APPLICATION BRANCH**
Filed September 12, 2003 : Attorney Docket No. 2003-1305

METHOD AND APPARATUS FOR
PLATING SUBSTRATE WITH COPPER
(Rule 1.53(b) Divisional
of Serial No. 09/492,138,
Filed January 27, 2000)

THE COMMISSIONER IS AUTHORIZED
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CLAIM OF PRIORITY UNDER 35 USC 119

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Sir:

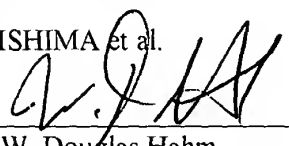
Applicants in the above-entitled application hereby claim the date of priority under the International Convention of Japanese Patent Application No. 17208/1999, filed January 26, 1999, and Japanese Patent Application No. 94943/1999, filed April 1, 1999, as acknowledged in the Declaration of this application.

A certified copy of said Japanese Patent Applications are of record in parent application Serial No. 09/492,138, filed January 27, 2000.

Respectfully submitted,

Koji MISHIMA et al.

By



W. Douglas Hahm
Registration No. 44,142
Attorney for Applicants

WDH/gtg
Washington, D.C. 20006-1021
Telephone (202) 721-8200
Facsimile (202) 721-8250
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